DISCRETE SEMICONDUCTORS

DATA SHEET

BFG31PNP 5 GHz wideband transistor

Product specification Supersedes data of November 1992 File under Discrete Semiconductors, SC14 1995 Sep 12





PNP 5 GHz wideband transistor

BFG31

FEATURES

- · High output voltage capability
- High gain bandwidth product
- · Good thermal stability
- Gold metallization ensures excellent reliability.

PIN	DESCRIPTION	
1	emitter	
2	base	
3	emitter	
4	collector	

PINNING

1 2 3 Top view MSB002 - 1 Fig.1 SOT223.

DESCRIPTION

PNP planar epitaxial transistor mounted in a plastic SOT223 envelope.

It is intended for wideband amplifier applications.

NPN complement is the BFG97.

QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V _{CEO}	collector-emitter voltage	open base	_	_	-15	V
I _C	DC collector current		_	_	-100	mA
P _{tot}	total power dissipation	up to $T_s = 135$ °C; note 1	_	_	1	W
h _{FE}	DC current gain	$I_{C} = -70 \text{ mA}; V_{CE} = -10 \text{ V};$ $T_{amb} = 25 \text{ °C}$	25	_	_	
f _T	transition frequency	$I_{C} = -70 \text{ mA}; V_{CE} = -10 \text{ V};$ $f = 500 \text{ MHz}; T_{amb} = 25 ^{\circ}\text{C}$	_	5.0	_	GHz
G _{UM}	maximum unilateral power gain	$I_{C} = -70 \text{ mA}; V_{CE} = -10 \text{ V};$ $f = 800 \text{ MHz}; T_{amb} = 25 ^{\circ}\text{C}$	_	12	_	dB
Vo	output voltage	$I_{C} = -100 \text{ mA}; V_{CE} = -10 \text{ V};$ $R_{L} = 75 \Omega; T_{amb} = 25 ^{\circ}C$	_	600	_	mV

LIMITING VALUES

In accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{CBO}	collector-base voltage	open emitter	_	-20	V
V _{CEO}	collector-emitter voltage	open base	_	-15	V
V _{EBO}	emitter-base voltage	open collector	_	-3	V
I _C	DC collector current		_	-100	mA
P _{tot}	total power dissipation	up to T _s = 135 °C; note 1	_	1	W
T _{stg}	storage temperature		-65	150	°C
T _i	junction temperature		_	175	°C

Note

1. T_s is the temperature at the soldering point of the collector tab.

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THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	THERMAL RESISTANCE
R _{th j-s}	thermal resistance from junction to soldering point	up to $T_s = 135$ °C; note 1	40 K/W

Note

1. T_s is the temperature at the soldering point of the collector tab.

CHARACTERISTICS

 $T_i = 25$ °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V _{(BR)CBO}	collector-base breakdown voltage	open emitter; I _C = -10 mA	-20	-	-	٧
V _{(BR)CEO}	collector-emitter breakdown voltage	open base; I _C = −10 mA	-18	_	_	٧
V _{(BR)EBO}	emitter-base breakdown voltage	open collector; I _E = -0.1 mA	-3	_	_	V
I _{CBO}	collector cut-off current	I _E = 0; V _{CB} = -10 V	_	_	-1	μΑ
h _{FE}	DC current gain	$I_C = -70 \text{ mA}; V_{CE} = -10 \text{ V};$ $T_{amb} = 25 \text{ °C}$	25	_	_	
C _{cb}	collector-base capacitance	$I_C = 0$; $V_{CB} = -10 \text{ V}$; $f = 1 \text{ MHz}$;	_	1.8	_	pF
C _{eb}	emitter-base capacitance	$I_C = 0$; $V_{EB} = -10 \text{ V}$; $f = 1 \text{ MHz}$	_	5	_	pF
C _{re}	feedback capacitance	$I_C = 0$; $V_{CE} = -10 \text{ V}$; $f = 1 \text{ MHz}$; $T_{amb} = 25 \text{ °C}$	_	1.6	_	pF
f _T	transition frequency	$I_C = -70 \text{ mA}; V_{CE} = -10 \text{ V};$ f = 500 MHz; $T_{amb} = 25 ^{\circ}\text{C}$	_	5	_	GHz
G _{UM}	maximum unilateral power gain; note 1	$I_C = -70 \text{ mA}; V_{CE} = -10 \text{ V};$ $f = 500 \text{ MHz}; T_{amb} = 25 ^{\circ}\text{C}$	_	16	_	dB
		I _C = -70 mA; V _{CE} = -10 V; f = 800 MHz; T _{amb} = 25 °C	_	12	_	dB
Vo	output voltage	note 2	_	600	_	mV
Vo	output voltage	note 3	_	550	_	mV

Notes

1. G_{UM} is the maximum unilateral power gain, assuming S_{12} is zero and $G_{UM} = 10 \log \frac{|s_{21}|^2}{(1-|s_{11}|^2)(1-|s_{22}|^2)}$ dB.

2. d_{im} = -60 dB; I_C = -70 mA; V_{CE} = -10 V; R_L = 75 Ω ; T_{amb} = 25 °C;

$$\begin{split} V_p &= V_o \text{ at } d_{im} = -60 \text{ dB; } f_p = 850.25 \text{ MHz;} \\ V_q &= V_o - 6 \text{ dB; } f_q = 858.25 \text{ MHz;} \end{split}$$

 $V_r = V_o - 6 \text{ dB}; f_r = 860.25 \text{ MHz};$

measured at $f_{(p+q-r)} = 848.25 \text{ MHz}.$

3. $d_{im} = -60 \text{ dB (DIN 45004B)}$; $I_C = -70 \text{ mA}$; $V_{CE} = -10 \text{ V}$; $R_L = 75 \Omega$; $T_{amb} = 25 \,^{\circ}\text{C}$;

 $V_p = V_o = at d_{im} = -60 dB; f_p = 445.25 MHz;$

 $V_q = V_o - 6 \text{ dB}$; $f_q = 453.25 \text{ MHz}$;

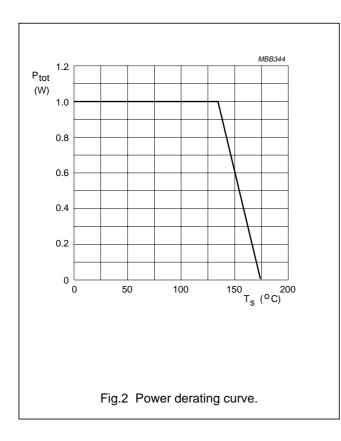
 $V_r = V_o - 6 \text{ dB}$; $f_r = 455.25 \text{ MHz}$;

measured at $f_{(p+q-r)} = 443.25$ MHz.

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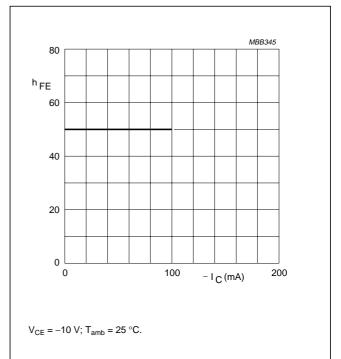
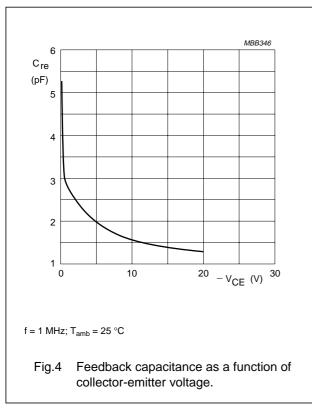
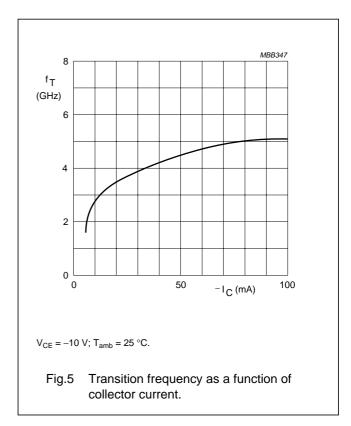


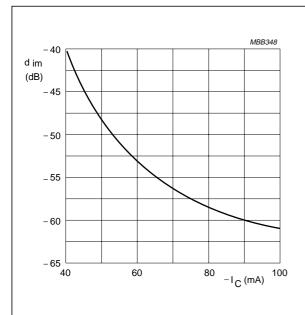
Fig.3 DC current gain as a function of collector current.





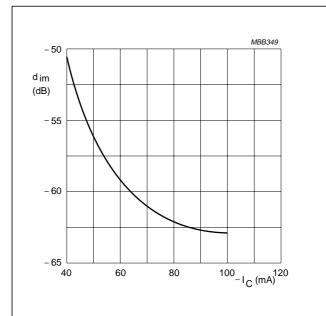
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 $V_{CE} = -10 \text{ V; } V_o = 650 \text{ mV; } T_{amb} = 25 \text{ °C; } \\ f_{(p+q-r)} = 443.25 \text{ MHz.}$

Fig.6 Intermodulation distortion as a function of collector current.



 $V_{CE} = -10 \text{ V}; V_{o} = 550 \text{ mV}; T_{amb} = 25 \text{ °C}; f_{(p+q-r)} = 848.25 \text{ MHz}.$

Fig.7 Intermodulation distortion as a function of collector current.

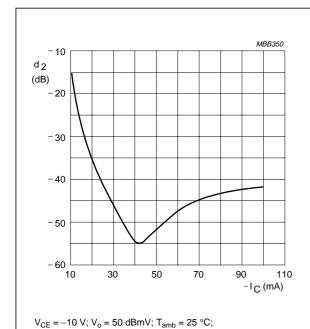
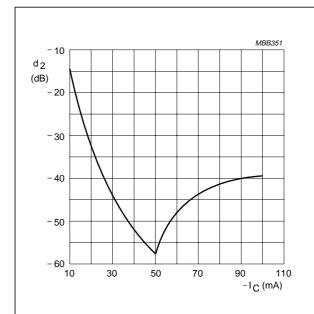


Fig.8 Second order intermodulation distortion

as a function of collector current.



 $V_{CE} = -10 \text{ V; } V_o = 50 \text{ dBmV; } T_{amb} = 25 \text{ }^{\circ}\text{C;} \\ f_{(p+q)} = 810 \text{ MHz.}$

Fig.9 Second order intermodulation distortion as a function of collector current.

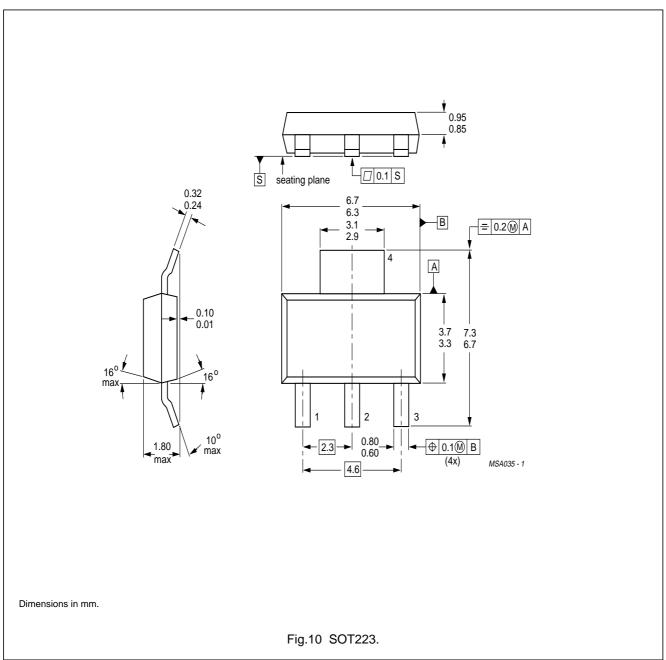
 $f_{(p+q)} = 450 \text{ MHz}.$

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PACKAGE OUTLINE



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DEFINITIONS

Data sheet status	
Objective specification	This data sheet contains target or goal specifications for product development.
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.
Product specification	This data sheet contains final product specifications.
Limiting values	

Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

Application information

Where application information is given, it is advisory and does not form part of the specification.

LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.

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